

AMENDMENTS

In the Claims:

This listing of claims replaces all prior versions, and listings, of claims in the application.

1-36. (Canceled)

37. (Currently Amended) A circuit component built-in module comprising:
an insulating substrate formed of a mixture comprising an inorganic filler and a thermosetting resin;
a plurality of wiring patterns formed on at least one principal plane of the insulating substrate;
an active component buried in the insulating substrate and electrically connected to at least one of the wiring patterns; and
a passive component buried in the insulating substrate and electrically connected to at least one of the wiring patterns;
wherein the active component is electrically connected to the passive component by the wiring patterns and the insulating substrate has a coefficient of linear expansion of $8 \times 10^{-6}/^{\circ}\text{C}$ to $20 \times 10^{-6}/^{\circ}\text{C}$ and a heat conductivity of 1w/mK to 10w/mK.

38. (Previously Presented) A circuit component built-in module according to claim 37, comprising an inner via formed in the insulating substrate and electrically connected to the wiring patterns.

39. (Currently Amended) A circuit component built-in module according to claim 37, wherein 70 wt % to 95 wt % of the mixture comprises the inorganic filler ~~and the thermosetting resin.~~

40. (Previously Presented) A circuit component built-in module according to claim 37, wherein the wiring patterns are formed on the principal plane and in an internal portion of the insulating substrate.

41. (Previously Presented) A circuit component built-in module according to claim 38, wherein the inner via is formed of a conductive resin composition.

42. (Previously Presented) A circuit component built-in module according to claim 37, wherein the circuit component is shielded from external air by the insulating substrate.

43. (Previously Presented) A circuit component built-in module according to claim 37, wherein the thermosetting resin comprises at least one thermosetting resin selected from the group consisting of an epoxy resin, a phenol resin and a cyanate resin.

44. (Previously Presented) A circuit component built-in module according to claim 37, wherein the inorganic filler comprises at least one inorganic filler selected from the group consisting of Al_2O_3 , MgO , BN , AlN and SiO_2 .

45. (Previously Presented) A circuit component built-in module according to claim 37, wherein an average particle diameter of the inorganic filler is $0.1\mu\text{m}$ to $100\mu\text{m}$.

46. (Previously Presented) A circuit component built-in module according to claim 37, wherein the wiring patterns comprise at least one conductive substance selected from the group consisting of copper and a conductive resin composition.

47. (Previously Presented) A circuit component built-in module according to claim 37, wherein the wiring patterns comprise lead frames formed by etching or stamping.

48. (Previously Presented) A circuit component built-in module according to claim 37, wherein the circuit component comprises at least one component selected from the group consisting of a chip resistor, a chip capacitor and a chip inductor.

49. (Previously Presented) A circuit component built-in module according to claim 37, wherein the mixture further comprises at least one additive selected from the group consisting of a dispersant, a coloring agent, a coupling agent and a releasing agent.

50. (Cancelled)

51. (Previously Presented) A circuit component built-in module according to claim 37, wherein the active component comprises a semiconductor bare chip, and the semiconductor bare chip is flip-chip bonded onto the wiring pattern.

52. (Currently Amended) A circuit component built-in module according to claim ~~37~~41, wherein the conductive resin composition comprises metal particles of at least one metal selected from the group consisting of gold, silver, copper and nickel as a conductive component, and an epoxy resin as a resin component.

53. (New) A circuit component built-in module according to claim 37, wherein the wiring patterns comprise a conductive resin composition and the conductive resin composition comprises metal particles of at least one metal selected from the group consisting of gold, silver, copper and nickel as a conductive component, and an epoxy resin as a resin component.